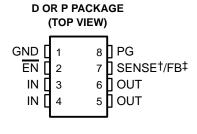
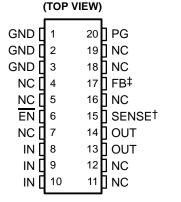
- Available in 5-V, 4.85-V, and 3.3-V
 Fixed-Output and Adjustable Versions
- Very Low-Dropout Voltage . . . Maximum of 32 mV at I_O = 100 mA (TPS7150)
- Very Low Quiescent Current Independent of Load . . . 285 μA Typ
- Extremely Low Sleep-State Current 0.5 μA Max
- 2% Tolerance Over Specified Conditions For Fixed-Output Versions
- Output Current Range of 0 mA to 500 mA
- TSSOP Package Option Offers Reduced Component Height for Space-Critical Applications
- Power-Good (PG) Status Output

description

The TPS71xx integrated circuits are a family of micropower low-dropout (LDO) voltage regulators. An order of magnitude reduction in dropout voltage and quiescent current over conventional LDO performance is achieved by replacing the typical pnp pass transistor with a PMOS device.



PW PACKAGE



NC – No internal connection † SENSE – Fixed voltage options only (TPS7133, TPS7148, and TPS7150) ‡ FB – Adjustable version only (TPS7101)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (maximum of 32 mV at an output current of 100 mA for the TPS7150) and is directly proportional to the output current (see Figure 1). Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and remains independent of output loading (typically 285 μ A over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. The LDO family also features a sleep mode; applying a TTL high signal to $\overline{\text{EN}}$ (enable) shuts down the regulator, reducing the quiescent current to 0.5 μ A maximum at $T_{\text{L}} = 25^{\circ}\text{C}$.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

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description (continued)

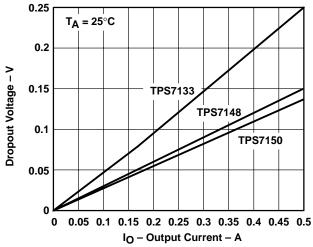


Figure 1. Dropout Voltage Versus Output Current

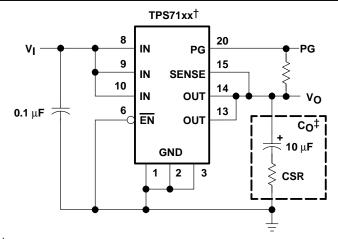
Power good (PG) reports low output voltage and can be used to implement a power-on reset or a low-battery indicator.

The TPS71xx is offered in 3.3-V, 4.85-V, and 5-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.2 V to 9.75 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges (3% for adjustable version). The TPS71xx family is available in PDIP (8 pin), SO (8 pin), and TSSOP (20-pin) packages. The TSSOP has a maximum height of 1,2 mm.

AVAILABLE OPTIONS

т.	OUTP	UT VOLT (V)	AGE	PAG	CKAGED DEVICE	:S	CHIP FORM
TJ	MIN	TYP	MAX	SMALL OUTLINE PLASTIC DIP TSSOP (PW)			(Y)
	4.9	5	5.1	TPS7150QD	TPS7150QP	TPS7150QPW	TPS7150Y
	4.75	4.85	4.95	TPS7148QD	TPS7148QP	TPS7148QPW	TPS7148Y
-40°C to 125°C	3.23	3.3	3.37	TPS7133QD	TPS7133QP	TPS7133QPW	TPS7133Y
		djustable ¹ V to 9.75		TPS7101QD	TPS7101QP	TPS7101QPW	TPS7101Y

[†]The D and PW packages are available taped and reeled. Add R suffix to device type (e.g., TPS7150QDR). The TPS7101Q is programmable using an external resistor divider (see application information). The chip form is tested at 25°C.

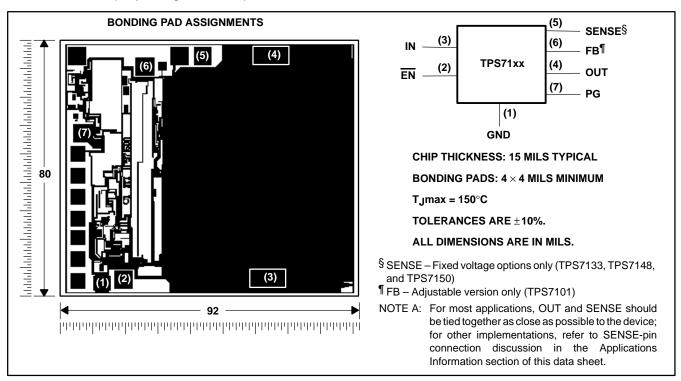


- † TPS7133, TPS7148, TPS7150 (fixed-voltage options)
- ‡ Capacitor selection is nontrivial. See application information section for details.

Figure 2. Typical Application Configuration

TPS71xx chip information

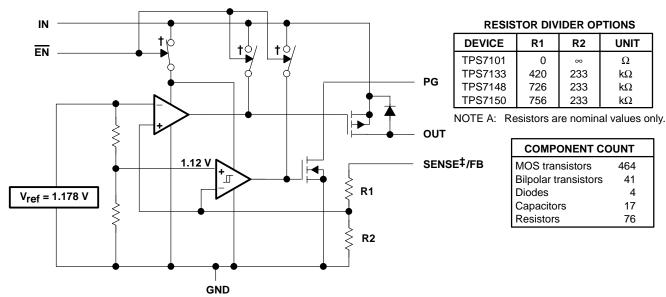
These chips, when properly assembled, display characteristics similar to the TPS71xxQ. Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y OW-DROPOUT VOLTAGE REGULATORS.

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functional block diagram



[†] Switch positions are shown with EN low (active).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Input voltage range¶, V _I , PG, SENSE, EN	0.3 V to 11 V
Output current, IO	
Continuous total power dissipation	See Dissipation Rating Tables 1 and 2
Operating virtual junction temperature range, T _J	–55°C to 150°C
Storage temperature range, T _{Stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[§] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE 1 - FREE-AIR TEMPERATURE (see Figure 3)#

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	145 mW
Р	1175 mW	9.4 mW/°C	752 mW	235 mW
PWII	700 mW	5.6 mW/°C	448 mW	140 mW

DISSIPATION RATING TABLE 2 - CASE TEMPERATURE (see Figure 4)#

PACKAGE	$T_C \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _C = 25°C	T _C = 70°C POWER RATING	T _C = 125°C POWER RATING
D	2188 mW	17.5 mW/°C	1400 mW	438 mW
Р	2738 mW	21.9 mW/°C	1752 mW	548 mW
PWII	4025 mW	32.2 mW/°C	2576 mW	805 mW

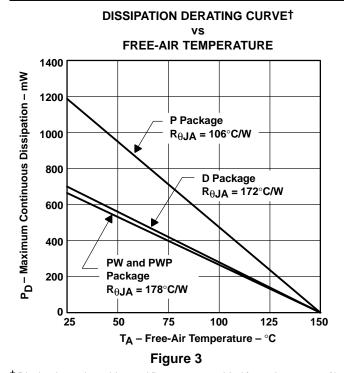
[#]Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

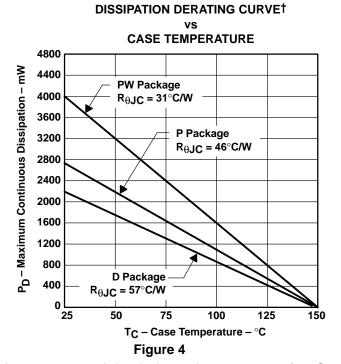
Refer to Thermal Information section for detailed power dissipation considerations when using the TSSOP packages.



[‡] For most applications, SENSE should be externally connected to OUT as close as possible to the device. For other implementations, refer to SENSE-pin connection discussion in Applications Information section.

 $[\]P$ All voltage values are with respect to network terminal ground.





[†] Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

recommended operating conditions

		MIN	MAX	UNIT
	TPS7101Q	2.5	10	
Innut valtage M.T	TPS7133Q	3.77	10] _v
Input voltage, V _I ‡	TPS7148Q	5.2	10	1 ^v
	TPS7150Q	5.33	10	1
High-level input voltage at EN, V _{IH}		2		V
Low-level input voltage at EN, V _{IL}			0.5	V
Output current range, IO		0	500	mA
Operating virtual junction temperature rar	ge, TJ	-40	125	°C

[‡] Minimum input voltage defined in the recommended operating conditions is the maximum specified output voltage plus dropout voltage at the maximum specified load range. Since dropout voltage is a function of output current, the usable range can be extended for lighter loads. To calculate the minimum input voltage for your maximum output current, use the following equation: $V_{I(min)} = V_{O(max)} + V_{DO(max load)}$. Because the TPS7101 is programmable, $v_{DO(max)}$ should be used to calculate $v_{DO(max)}$ before applying the above equation. The equation for calculating $v_{DO(max)}$ is given in Note 2 in the electrical characteristics table. The minimum value of 2.5 V is the absolute lower limit for the recommended input voltage range for the TPS7101.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

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electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CONI	DITIONS‡	ТЈ		1Q, TPS 8Q, TPS		UNIT	
				MIN	TYP	MAX		
Ground current (active mode)	<u>EN</u> ≤ 0.5 V,	$V_{I} = V_{O} + 1 V_{r}$	25°C		285	350	μА	
Ground current (active mode)	$0~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA}$		-40°C to 125°C			460	μΑ	
Input current (standby mode)	EN = VI,	2.7 V ≤ V _I ≤ 10 V	25°C			0.5	μА	
mput current (standby mode)	EN = VI,	2.7 V 3 V 3 10 V	-40°C to 125°C			2	μΑ	
Output current limit	V _O = 0,	V _I = 10 V	25°C		1.2	2	A	
Output current limit	V() = 0,	v = 10 v	-40°C to 125°C			2	Α .	
Pass-element leakage current in standby	$\overline{EN} = V_{I},$	271/21/2101/	25°C			0.5		
mode	EIV = VI,	2.7 V ≤ V _I ≤ 10 V	-40°C to 125°C			1	μΑ	
PG leakage current	Normal operation,	Vpg = 10 V	25°C		0.02	0.5	μΑ	
	Normal operation,		-40°C to 125°C			0.5	μΑ	
Output voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C	
Thermal shutdown junction temperature					165		°C	
ENLIGHT AND ACTOR Albert and all and all and all all all and all all all all all all all all all al	$2.5 \text{ V} \leq \text{V}_{\text{I}} \leq 6 \text{ V}$		-40°C to 125°C	2			V	
EN logic high (standby mode)	6 V ≤ V _I ≤ 10 V		-40 C to 125 C	2.7]	
EN la via la confection and de)	271/21/2401/		25°C			0.5	V	
EN logic low (active mode)	2.7 V ≤ V _I ≤ 10 V		-40°C to 125°C			0.5	l ^v	
EN hysteresis voltage			25°C		50		mV	
<u> </u>	0.1/ < 1/ < 40.1/	01/21/2401/	25°C	-0.5		0.5		
EN input current	0 V ≤ V _I ≤ 10 V	0 V ≤ V _I ≤ 10 V	-40°C to 125°C	-0.5		0.5	μΑ	
Minimum V. for active page clares			25°C		2.05	2.5	V	
Minimum V _I for active pass element			-40°C to 125°C			2.5	ľ	
Minimum V. for valid DC	I 200 ·· A	I 200 ·· A	25°C		1.06	1.5		
Minimum V _I for valid PG	lpG = 300 μA	I _{PG} = 300 μA	-40°C to 125°C			1.9	٧	

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to CO.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101 electrical characteristics at I_O = 10 mA, V_I = 3.5 V, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR † = 1 Ω , FB shorted to OUT at device leads (unless otherwise noted)

DADAMETER	TEST COL	т.	TPS7101Q			UNIT	
PARAMETER	TEST COI	NDITIONS‡	TJ	MIN	TYP	MAX	UNII
Reference voltage (measured at FB	V _I = 3.5 V,	I _O = 10 mA	25°C		1.178		V
with OUT connected to FB)	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$5 \text{ mA} \le I_O \le 500 \text{ mA},$	-40°C to 125°C	1.143		1.213	V
Reference voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C
	V: 0.4.V	50 A < l = < 450 m A	25°C		0.7	1	
	$V_{I} = 2.4 V,$	$50 \mu\text{A} \le \text{I}_{\text{O}} \le 150 \text{mA}$	-40°C to 125°C			1	1
Pass-element series resistance (see Note 2)	V _I = 2.4 V,	150 mA ≤ I _O ≤ 500	25°C		0.83	1.3]
	V = 2.4 V,	mA	-40°C to 125°C			1.3	Ω
	V _I = 2.9 V,	50 μA ≤ I _O ≤ 500 mA	25°C		0.52	0.85	
	V = 2.9 V,	20 μA ≥ 1Q ≥ 200 IIIA	-40°C to 125°C			0.85	
	V _I = 3.9 V,	$50~\mu\text{A} \leq I_{\mbox{O}} \leq 500~m\text{A}$	25°C		0.32		
	V _I = 5.9 V,	$50~\mu\text{A} \leq I_O \leq 500~\text{mA}$	25°C		0.23		
Input regulation	$V_{I} = 2.5 \text{ V to } 10 \text{ V},$	$50 \mu A \le I_0 \le 500 \text{ mA},$	25°C			18	mV
input regulation	See Note 1		-40°C to 125°C			25	1117
	$I_O = 5 \text{ mA to } 500 \text{ mA},$		25°C			14	mV mV
	See Note 1		-40°C to 125°C			25	
Catput regulation	$I_0 = 50 \mu\text{A} \text{ to } 500 \text{mA},$		25°C			22	
	See Note 1		-40°C to 125°C			54	111 V
		IO = 50 !! A	25°C	48	59		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	44			dB
Tripple rejection	1 = 120112	$I_O = 500 \text{ mA},$	25°C	45	54		"
		See Note 1	-40°C to 125°C	44			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√Hz
	4011- 46 4400111-	$C_{O} = 4.7 \mu F$	25°C		95		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	$C_{O} = 10 \mu F$	25°C		89		μVrms
		$C_{O} = 100 \mu F$	25°C		74		
PG trip-threshold voltage§	VFB voltage decreasing	g from above V _{PG}	-40°C to 125°C	1.101		1.145	V
PG hysteresis voltage§	Measured at V _{FB}		25°C		12		mV
20	400 4	V 0.40 V	25°C		0.1	0.4	.,
PG output low voltage§	$I_{PG} = 400 \mu A$	V _I = 2.13 V	-40°C to 125°C			0.4	' '
ED 's most suggest to			25°C	-10	0.1	10	
FB input current			-40°C to 125°C	-20		20	nA

TCSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

 $V_{DO} = I_O \cdot r_{DS(on)}$

 $r_{DS(on)}$ is a function of both output current and input voltage. The parametric table lists $r_{DS(on)}$ for $V_I = 2.4$ V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When V_I < 2.9 V and I_O > 150 mA simultaneously, pass element r_{DS(on)} increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

^{2.} To calculate dropout voltage, use equation:

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TPS7133 electrical characteristics at I_O = 10 mA, V_I = 4.3 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

2424455	TEOT 001	TEST CONDITIONS‡			PS71330	TPS7133Q		
PARAMETER	IEST CON	IDITIONS+	TJ	MIN	TYP	MAX	UNIT	
Output voltage	V _I = 4.3 V,	I _O = 10 mA	25°C		3.3		V	
Output voltage	$4.3 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	3.23		3.37	V	
	IO = 10 mA,	V ₁ = 2.22 V	25°C		4.5	7		
	IO = 10 IIIA,	V _I = 3.23 V	-40°C to 125°C			8		
Dropout voltage	IO = 100 mA,	V _I = 3.23 V	25°C		47	60	mV	
Dropout voltage	10 = 100 mA,	V = 3.23 V	-40°C to 125°C			80	IIIV	
	I _O = 500 mA,	V _I = 3.23 V	25°C		235	300		
	10 = 300 mA,	V = 3.23 V	-40°C to 125°C			400		
Pass-element series resistance	(3.23 V – V _O)/I _O ,	V _I = 3.23 V,	25°C		0.47	0.6	Ω	
Pass-element series resistance	$I_O = 500 \text{ mA}$		-40°C to 125°C			0.8	22	
Input regulation	V _I = 4.3 V to 10 V,	50 μ A ≤ I _O ≤ 500 mA	25°C			20	mV	
input regulation	v = 4.3 v to 10 v,	30 μA 3 10 3 300 111A	-40°C to 125°C			27	IIIV	
Output regulation	$I_O = 5$ mA to 500 mA,	$4.3 \text{ V} \le \text{V}_{1} \le 10 \text{ V}$	25°C		21	38	mV	
			-40°C to 125°C			75		
Output regulation	$I_{O} = 50 \mu\text{A} \text{ to } 500 \text{mA},$	121/21/2101/	25°C		30	60	mV	
	ΙΟ = 30 μΑ το 300 πΑ,	4.3 V \(\leq \text{V} \ \leq 10 V	-40°C to 125°C			120	IIIV	
		ΙΟ = 50 μΑ	25°C	43	54			
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	40			dB	
Ripple rejection	1 = 120112	I _O = 500 mA	25°C	39	49		ub	
		10 = 300 IIIA	-40°C to 125°C	36				
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz	
		$C_O = 4.7 \mu F$	25°C		274			
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		228		μVrms	
	001(1 = 1 32	C _O = 100 μF	25°C		159			
PG trip-threshold voltage	V _O voltage decreasing	from above V _{PG}	-40°C to 125°C	2.868		3	V	
PG hysteresis voltage			25°C		35		mV	
DC autout lauruslitana	1 4 4	V 0.0V	25°C		0.22	0.4	V	
PG output low voltage	$I_{PG} = 1 \text{ mA},$	V _I = 2.8 V	-40°C to 125°C			0.4	V V	

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7148 electrical characteristics at I_O = 10 mA, V_I = 5.85 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

			_	TF	UNIT		
PARAMETER	TEST CON	IDITIONS+	TJ	MIN	TYP	MAX	UNIT
Output valtage	V _I = 5.85 V,	I _O = 10 mA	25°C		4.85		V
Output voltage	$5.85 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	4.75		4.95	l ^v
	In 10 mA	\\. 4.75.\\	25°C		2.9	6	
	$I_{O} = 10 \text{ mA},$	V _I = 4.75 V	-40°C to 125°C			8	1
Decreased welfares	Jo - 100 mA	\\ 4.75.\\	25°C		30	37	mV
Dropout voltage	$I_0 = 100 \text{ mA},$	V _I = 4.75 V	-40°C to 125°C			54	IIIV
	In 500 mA	\/. 4.75.\/	25°C		150	180	1
	$I_{O} = 500 \text{ mA},$	V _I = 4.75 V	-40°C to 125°C			250	1
Dage element series resistance	(4.75 V – V _O)/I _O ,	V _I = 4.75 V,	25°C		0.32	0.35	Ω
Pass-element series resistance	$I_{O} = 500 \text{ mA}$		-40°C to 125°C			0.52	1 12
lanut regulation	V. 5.95 V to 40 V	50 μA ≤ I _O ≤ 500 mA	25°C			27	mV
Input regulation	$V_{I} = 5.85 \text{ V to } 10 \text{ V},$	30 μΑ ≤ 10 ≤ 300 111Α	-40°C to 125°C			37	l mv
	$I_O = 5$ mA to 500 mA,	5.85 V ≤ V _I ≤ 10 V	25°C		12	42	mV
Output regulation			-40°C to 125°C			80	1 1111
Output regulation	$I_{O} = 50 \mu\text{A} \text{ to } 500 \text{mA},$	5 95 V < V < 10 V	25°C		42	60	mV
	$IO = 50 \mu A to 500 mA$	5.05 V ≤ V ≤ 10 V	-40°C to 125°C			130	IIIV
		15 FO A	25°C	42	53		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	39			dB
Ripple rejection	1 = 120112	I _O = 500 mA	25°C	39	50		l ub
		10 = 300 IIIA	-40°C to 125°C	35			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz
		$C_{O} = 4.7 \mu F$	25°C		410		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		328		μVrms
	0011 = 132	C _O = 100 μF	25°C		212		1
PG trip-threshold voltage	V _O voltage decreasing	from above V _{PG}	-40°C to 125°C	4.5		4.7	٧
PG hysteresis voltage			25°C		50		mV
	1		25°C	-	0.2	0.4	.,
PG output low voltage	IpG = 1.2 mA,	V _I = 4.12 V	-40°C to 125°C		-	0.4	٧

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.
‡ Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must

Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

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TPS7150 electrical characteristics at I_O = 10 mA, V_I = 6 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS‡	TJ	TF MIN	PS71500 TYP	MAX	UNIT
• • • •	V _I = 6 V,	I _O = 10 mA	25°C		5		.,
Output voltage	6 V ≤ V _I ≤ 10 V,	5 mA ≤ I _O ≤ 500 mA	-40°C to 125°C	4.9		5.1	V
			25°C		2.9	6	
	$I_O = 10 \text{ mA},$	V _I = 4.88 V	-40°C to 125°C			8	
	1 400 4	\/ 400\/	25°C		27	32	
Dropout voltage	$I_0 = 100 \text{ mA},$	V _I = 4.88 V	-40°C to 125°C			47	mV
	1- 500 mA	V: 4.00.V	25°C		146	170	
	$I_{O} = 500 \text{ mA},$	V _I = 4.88 V	-40°C to 125°C			230	
Dona element entire registeres	(4.88 V – V _O)/I _O ,	V _I = 4.88 V,	25°C		0.29	0.32	0
Pass-element series resistance	I _O = 500 mA	•	-40°C to 125°C			0.47	Ω
Innut so guidation	V _I = 6 V to 10 V,	$50 \mu A \le I_O \le 500 \text{mA}$	25°C			25	mV
Input regulation	V = 0 V (0 10 V)	20 hα ≥ 10 ≥ 200 μια	-40°C to 125°C			32	mv
Outrat as mulation	$I_O = 5$ mA to 500 mA,	6 V ≤ V _I ≤ 10 V	25°C		30	45	mV
			-40°C to 125°C			86	mv
Output regulation	$I_{O} = 50 \mu\text{A} \text{ to } 500 \text{mA},$	6 \/ < \/ < 10 \/	25°C		45	65	mV
	$10 = 30 \mu\text{A}$ to 300 mA,	0 v ≤ v ≤ 10 v	-40°C to 125°C			140	IIIV
		In - 50 A	25°C	45	55		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	40			dB
Rippie rejection	1 = 120112	I _O = 500 mA	25°C	42	52		ub
		10 = 300 IIIA	-40°C to 125°C	36			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz
		$C_{O} = 4.7 \mu\text{F}$	25°C		430		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		345		μVrms
	031(1 = 1 52	C _O = 100 μF	25°C		220		1
PG trip-threshold voltage	V _O voltage decreasing	from above Vpg	-40°C to 125°C	4.55		4.75	V
PG hysteresis voltage			25°C		53		mV
	1	.,	25°C		0.2	0.4	ι,,
PG output low voltage	$I_{PG} = 1.2 \text{ mA},$	$V_{ } = 4.25 \text{ V}$	-40°C to 125°C			0.4	V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 $\Omega,$ T $_{J}$ = 25°C, SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CONDITIONS‡	TPS7101Y, TPS7133Y TPS7148Y, TPS7150Y	UNIT
		MIN TYP MAX	
Ground current (active mode)	$\overline{\text{EN}} \le 0.5 \text{ V},$ $V_{\text{I}} = V_{\text{O}} + 1 \text{ V},$ $0 \text{ mA} \le I_{\text{O}} \le 500 \text{ mA}$	285	μΑ
Output current limit	$V_0 = 0,$ $V_1 = 10 V$	1.2	Α
PG leakage current	Normal operation, V _{PG} = 10 V	0.02	μΑ
Thermal shutdown junction temperature		165	°C
EN hysteresis voltage		50	mV
Minimum V _I for active pass element		2.05	V
Minimum V _I for valid PG	I _{PG} = 300 μA	1.06	V

PARAMETER	TEOT 06	TEST CONDITIONS‡		S7101Y	,	UNIT
PARAMETER	l iESI CC	ONDITIONS+	MIN	TYP	MAX	UNII
Reference voltage (measured at FB with OUT connected to FB)	V _I = 3.5 V,	I _O = 10 mA		1.178		V
	V _I = 2.4 V,	$50~\mu\text{A} \leq \text{I}_{O} \leq 150~\text{mA}$		0.7		
	V _I = 2.4 V,	$150~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA}$		0.83		
Pass-element series resistance (see Note 2)	$V_{\parallel} = 2.9 \text{ V},$	$50~\mu\text{A} \leq \text{I}_{O} \leq 500~\text{mA}$		0.52		Ω
	V _I = 3.9 V,	$50~\mu\text{A} \leq \text{I}_{\mbox{O}} \leq 500~\text{mA}$		0.32		
	V _I = 5.9 V,	$50~\mu\text{A} \leq \text{I}_{\mbox{O}} \leq 500~\text{mA}$		0.23		
Input regulation	V _I = 2.5 V to 10 V, See Note 1	$50 \mu A \le I_O \le 500 mA$,			18	mV
Outrot so sulption	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$I_O = 5$ mA to 500 mA,			14	mV
Output regulation	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$I_O = 50 \mu A \text{ to } 500 \text{ mA},$			22	mV
Ripple rejection	V _I = 3.5 V, I _O = 50 μA	f = 120 Hz,		59		dB
Output noise-spectral density	V _I = 3.5 V,	f = 120 Hz		2		μV/√ Hz
	V _I = 3.5 V,	$C_{O} = 4.7 \mu F$		95		
Output noise voltage	10 Hz ≤ f ≤ 100 kHz,	C _O = 10 μF		89		μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF	74			
PG hysteresis voltage§	V _I = 3.5 V,	Measured at V _{FB}		12		mV
PG output low voltage§	V _I = 2.13 V,	I _{PG} = 400 μA		0.1		V
FB input current	V _I = 3.5 V	V _I = 3.5 V		0.1		nA

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

2. To calculate dropout voltage, use equation:

 $V_{DO} = I_O \cdot r_{DS(on)}$

 $r_{DS(on)}$ is a function of both output current and input voltage. The parametric table lists $r_{DS(on)}$ for $V_I = 2.4$ V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When V_I < 2.9 V and I_O > 150 mA simultaneously, pass element r_{DS(on)} increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

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electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , T $_{J}$ = 25°C , SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED		TEST SOMBITIONS [‡]				UNIT
PARAMETER	TEST CC	TEST CONDITIONS [‡]				
Output voltage	$V_{I} = 4.3 V$	I _O = 10 mA		3.3		V
	V _I = 3.23 V,	I _O = 10 mA		0.02		
Dropout voltage	$V_{I} = 3.23 V$	$I_{O} = 100 \text{ mA}$		47		mV
	$V_{I} = 3.23 V$	I _O = 500 mA		235		
Pass-element series resistance	$(3.23 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 3.23 V,		0.47		Ω
Output regulation	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$	$I_O = 5$ mA to 500 mA	21			mV
Output regulation	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$	$I_{O} = 50 \mu\text{A} \text{ to } 500 \text{mA}$ 30			mV	
Dinnle rejection	V _I = 4.3 V,	ΙΟ = 50 μΑ	54			dB
Ripple rejection	f = 120 Hz	I _O = 500 mA				
Output noise-spectral density	$V_{I} = 4.3 V$	f = 120 Hz		2		μV/√Hz
	V _I = 4.3 V,	$C_{O} = 4.7 \mu\text{F}$		274		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	228 159		μVrms	
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF			1	
PG hysteresis voltage	V _I = 4.3 V			35		mV
PG output low voltage	V _I = 2.8 V,	Ipg = 1 mA		0.22		V

DADAMETER	TEOT OC	NDITIONO†	TF	UNIT		
PARAMETER	lesi co	ONDITIONS‡	MIN	TYP	MAX	UNIT
Output voltage	V _I = 5.85 V,	I _O = 10 mA		4.85		V
	V _I = 4.75 V,	I _O = 10 mA		0.08		
Dropout voltage	V _I = 4.75 V,	I _O = 100 mA		30		mV
	V _I = 4.75 V,	I _O = 500 mA		150		
Pass-element series resistance	$(4.75 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 4.75 V,		0.32		Ω
Output to guilation	5.85 V ≤ V _I ≤ 10 V,	$I_O = 5$ mA to 500 mA		12		mV
Output regulation	$5.85 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$I_O = 50 \mu A$ to 500 mA	42			mV
Dinnle rejection	V _I = 5.85 V,	ΙΟ = 50 μΑ	53			dB
Ripple rejection	f = 120 Hz	I _O = 500 mA		50		l ub
Output noise-spectral density	V _I = 5.85 V,	f = 120 Hz		2		μV/√ Hz
	V _I = 5.85 V,	$C_{O} = 4.7 \mu F$		410		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	328			μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF	212			
PG hysteresis voltage	V _I = 5.85 V	-		50		mV
PG output low voltage	V _I = 4.12 V,	I _{PG} = 1.2 mA		0.2	0.4	V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

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electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , T $_{J}$ = 25°C , SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED	7507.0	NIDITIONS [†]	TF	UNIT		
PARAMETER	TEST CO	TEST CONDITIONS [‡]				UNII
Output voltage	V _I = 6 V,	I _O = 10 mA		5		V
	V _I = 4.88 V,	I _O = 10 mA		0.13		
Dropout voltage	$V_{I} = 4.88 V$	I _O = 100 mA		27		mV
	$V_{I} = 4.88 V$	I _O = 500 μA		146		
Pass-element series resistance	$(4.88 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 4.88 V,		0.29		Ω
Output regulation	6 V ≤ V _I ≤ 10 V,	$I_O = 5 \text{ mA to } 500 \text{ mA}$		30		mV
Output regulation	6 V ≤ V _I ≤ 10 V,	$I_{O} = 50 \mu\text{A}$ to 500 mA		45		mV
Dinale rejection	V _I = 6 V,	ΙΟ = 50 μΑ		55		dB
Ripple rejection	f = 120 Hz	I _O = 500 mA	52			uБ
Output noise-spectral density	V _I = 6 V,	f = 120 Hz		2		μV/√ Hz
	V _I = 6 V,	C _O = 4.7 μF		430		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	345 220			μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF				1
PG hysteresis voltage	V _I = 6 V			53		mV
PG output low voltage	V _I = 4.25 V,	PG = 1.2 mA		0.2		V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

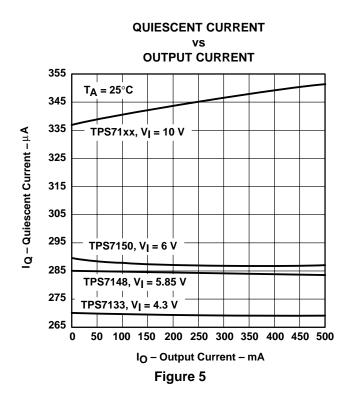


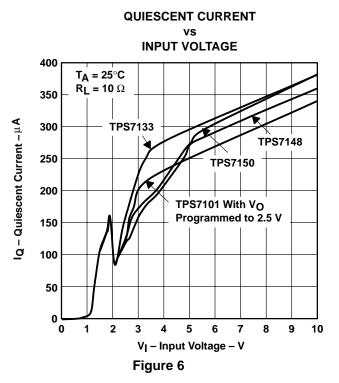
[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

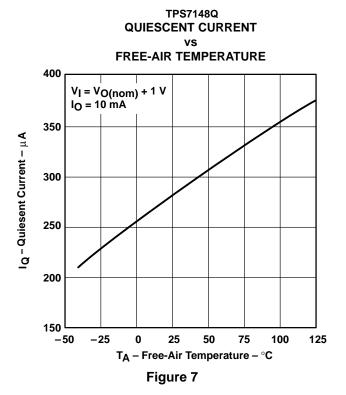
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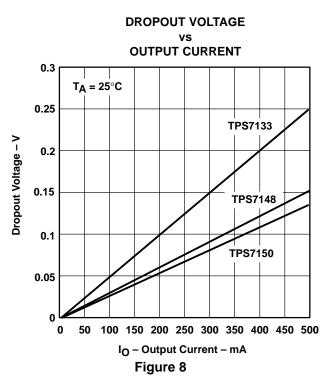
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CSR	Compensation series resistance	vs Added ceramic capacitance	41





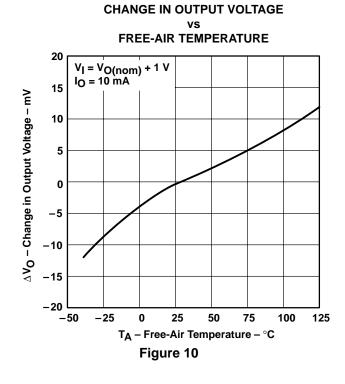


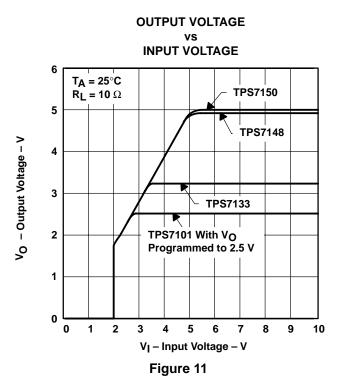


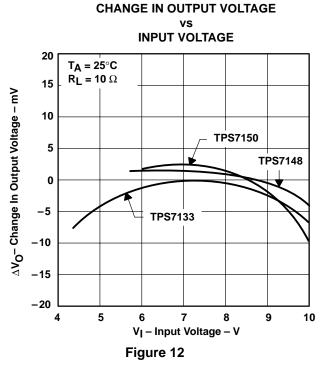


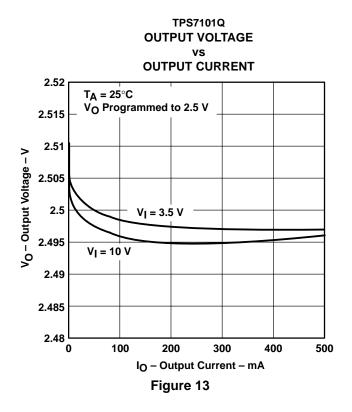
CHANGE IN DROPOUT VOLTAGE FREE-AIR TEMPERATURE 10 IO = 100 mA 8 Change in Dropout Voltage – mV 6 4 2 0 -2 -4 -6 -8 -10_50 -25 25 50 75 100 125 T_A - Free-Air Temperature - °C

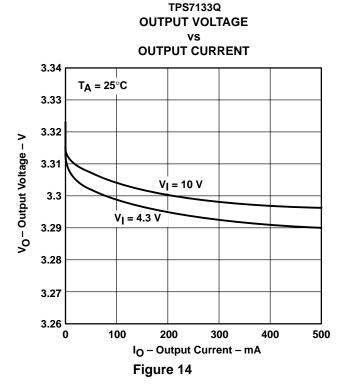
Figure 9

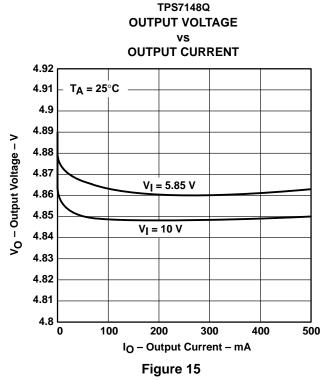


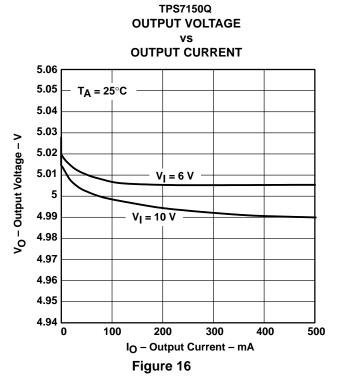












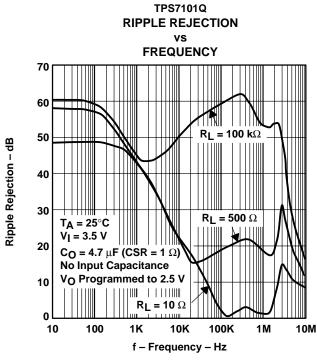
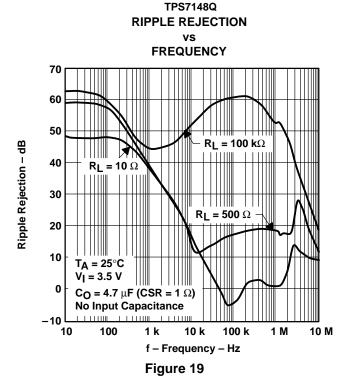
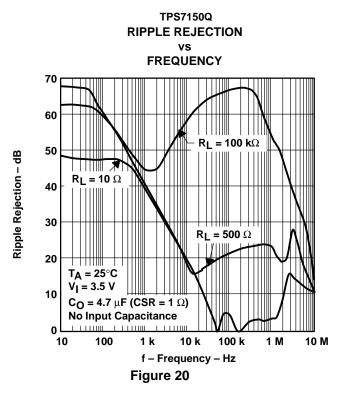


Figure 17



TPS7133Q RIPPLE REJECTION vs **FREQUENCY** 70 60 $R_L = 100 \text{ k}\Omega$ 50 Ripple Rejection – dB 40 30 $R_L = 500 \Omega$ 20 $R_L = 10 \Omega$ 10 $T_A = 25^{\circ}C$ $V_{I} = 3.5 V$ $C_0 = 4.7 \,\mu\text{F} (CSR = 1 \,\Omega)$ No Input Capacitance 100 10 k 10 100 k 1 M 10 M f - Frequency - Hz

Figure 18



TPS7101Q OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

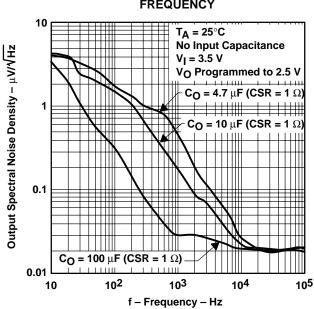


Figure 21

TPS7133Q OUTPUT SPECTRAL NOISE DENSITY VS FREQUENCY

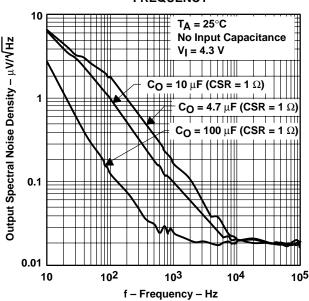


Figure 22

TPS7148Q OUTPUT SPECTRAL NOISE DENSITY vs

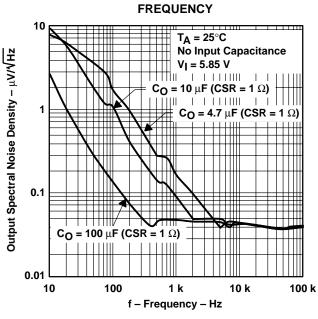


Figure 23

TPS7150Q OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

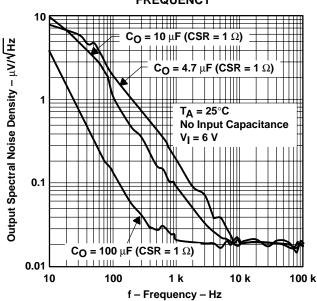
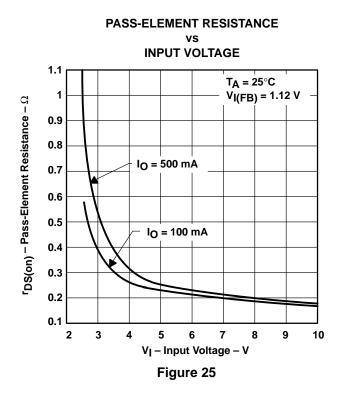
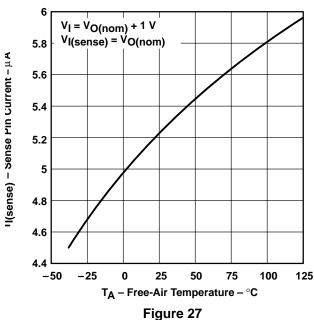


Figure 24

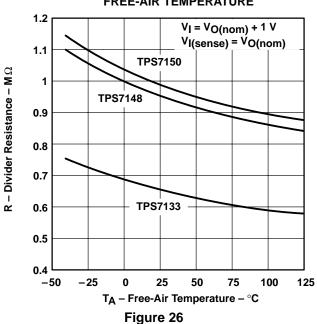


FIXED-OUTPUT VERSIONS SENSE PIN CURRENT

FREE-AIR TEMPERATURE

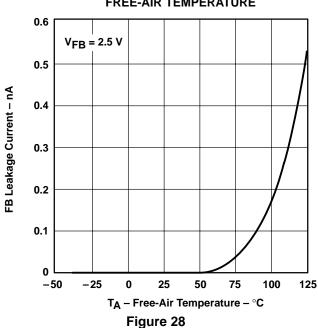


DIVIDER RESISTANCE vs FREE-AIR TEMPERATURE



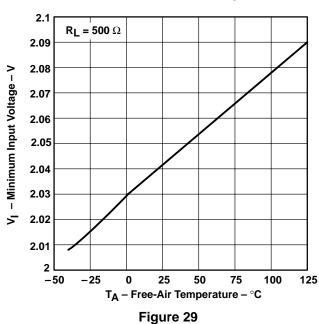
ADJUSTABLE VERSION FB LEAKAGE CURRENT

VS FREE-AIR TEMPERATURE



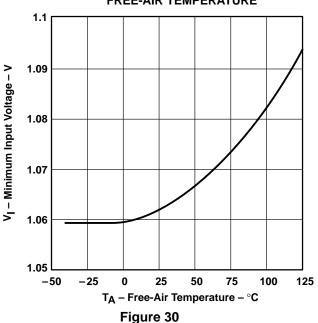
MINIMUM INPUT VOLTAGE FOR ACTIVE PASS ELEMENT

FREE-AIR TEMPERATURE



MINIMUM INPUT VOLTAGE FOR VALID POWER GOOD (PG)

vs FREE-AIR TEMPERATURE



EN INPUT CURRENT

FREE-AIR TEMPERATURE

100 $V_I = V_{I(\overline{EN})} = 10 \text{ V}$ 90 80 I_(EN) - Input Current - nA 70 60 50 40 30 20 10 0 -40 -20 20 40 60 80 100 120 140 T_A - Free-Air Temperature - °C

Figure 31



OUTPUT VOLTAGE RESPONSE FROM ENABLE (EN)

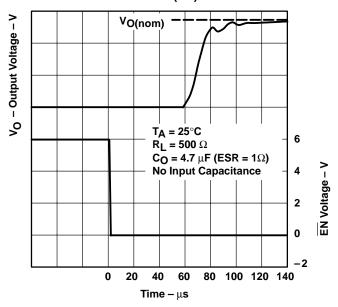


Figure 32

POWER-GOOD (PG) VOLTAGE

OUTPUT VOLTAGE

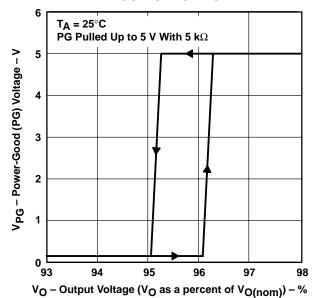
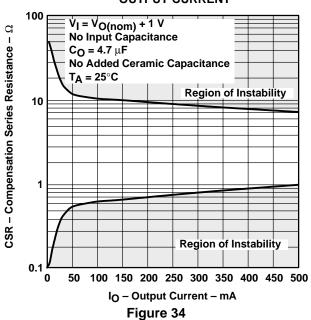


Figure 33



TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

vs OUTPUT CURRENT



TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

vs ADDED CERAMIC CAPACITANCE

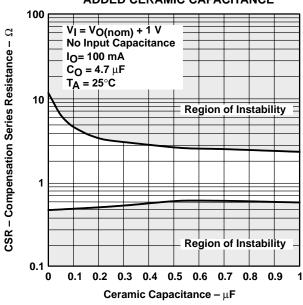


Figure 36

TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

vs OUTPUT CURRENT

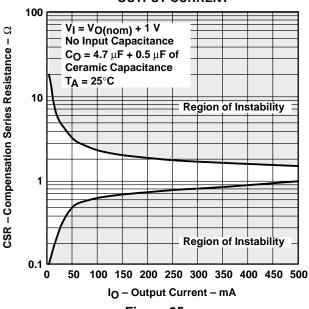


Figure 35

TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE

vs ADDED CERAMIC CAPACITANCE

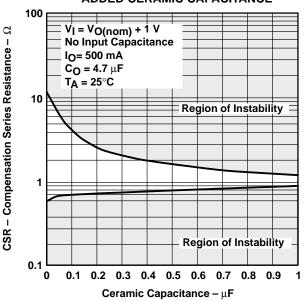


Figure 37

TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE vs

OUTPUT CURRENT

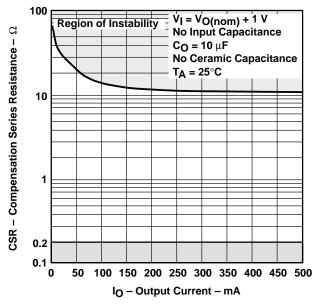


Figure 38

TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE

ADDED CERAMIC CAPACITANCE

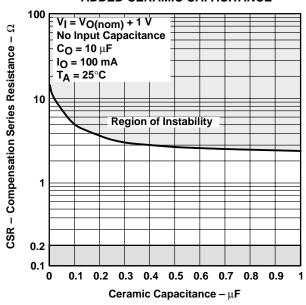
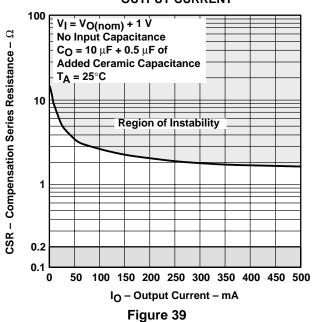


Figure 40

†CSR values below 0.1 Ω are not recommended.

TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE vs OUTPUT CURRENT



TYPICAL REGIONS OF STABILITY† COMPENSATION SERIES RESISTANCE

vs ADDED CERAMIC CAPACITANCE

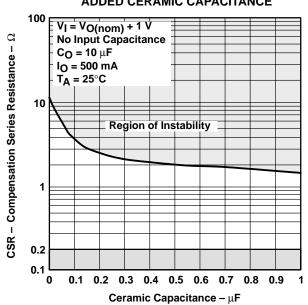


Figure 41



TYPICAL CHARACTERISTICS

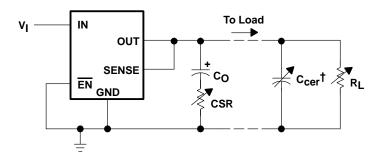


Figure 42. Test Circuit for Typical Regions of Stability (Figures 34 through 41)

† Ceramic capacitor

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

APPLICATION INFORMATION

The TPS71xx series of low-dropout (LDO) regulators is designed to overcome many of the shortcomings of earlier-generation LDOs, while adding features such as a power-saving shutdown mode and a power-good indicator. The TPS71xx family includes three fixed-output voltage regulators: the TPS7133 (3.3 V), the TPS7148 (4.85 V), and the TPS7150 (5 V). The family also offers an adjustable device, the TPS7101 (adjustable from 1.2 V to 9.75 V).

device operation

The TPS71xx, unlike many other LDOs, features very low quiescent currents that remain virtually constant even with varying loads. Conventional LDO regulators use a pnp-pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). Close examination of the data sheets reveals that those devices are typically specified under near no-load conditions; actual operating currents are much higher as evidenced by typical quiescent current versus load current curves. The TPS71xx uses a PMOS transistor to pass current; because the gate of the PMOS element is voltage driven, operating currents are low and invariable over the full load range. The TPS71xx specifications reflect actual performance under load.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS71xx quiescent current remains low even when the regulator drops out, eliminating both problems.

Included in the TPS71xx family is a 4.85-V regulator, the TPS7148. Designed specifically for 5-V cellular systems, its 4.85-V output, regulated to within \pm 2%, allows for operation within the low-end limit of 5-V systems specified to \pm 5% tolerance; therefore, maximum regulated operating lifetime is obtained from a battery pack before the device drops out, adding crucial talk minutes between charges.

The TPS71xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to under 2 μ A. If the shutdown feature is not used, $\overline{\text{EN}}$ should be tied to ground. Response to an enable transition is quick; regulated output voltage is reestablished in typically 120 μ s.

minimum load requirements

The TPS71xx family is stable even at zero load; no minimum load is required for operation.

SENSE-pin connection

The SENSE pin of fixed-output devices must be connected to the regulator output for proper functioning of the regulator. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit (remote sense) to improve performance at that point. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. Routing the SENSE connection to minimize/avoid noise pickup is essential. Adding an RC network between SENSE and OUT to filter noise is not recommended because it can cause the regulator to oscillate.

external capacitor requirements

An input capacitor is not required; however, a ceramic bypass capacitor (0.047 pF to 0.1 μ F) improves load transient response and noise rejection if the TPS71xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

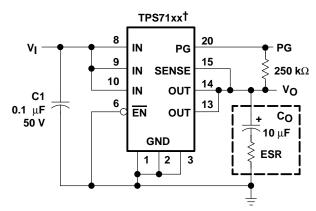


APPLICATION INFORMATION

external capacitor requirements (continued)

As with most LDO regulators, the TPS71xx family requires an output capacitor for stability. A 10- μ F solid-tantalum capacitor connected from the regulator output to ground is sufficient to ensure stability over the full load range (see Figure 43). Adding high-frequency ceramic or film capacitors (such as power-supply bypass capacitors for digital or analog ICs) can cause the regulator to become unstable unless the ESR of the tantalum capacitor is less than 1.2 Ω over temperature. Where component height and/or mounting area is a problem, physically smaller, 10- μ F devices can be screened for ESR. Figures 34 through 41 show the stable regions of operation using different values of output capacitance with various values of ceramic load capacitance.

In applications with little or no high-frequency bypass capacitance (< $0.2~\mu$ F), the output capacitance can be reduced to 4.7 μ F, provided ESR is maintained between the values shown in figures 34 through 41. Because minimum capacitor ESR is seldom if ever specified, it may be necessary to add a 0.5- Ω to 1- Ω resistor in series with the capacitor and limit ESR to $1.5~\Omega$ maximum.



† TPS7133, TPS7148, TPS7150 (fixed-voltage options)

Figure 43. Typical Application Circuit

programming the TPS7101 adjustable LDO regulator

Programming the adjustable regulators is accomplished using an external resistor divider as shown in Figure 44. The equation governing the output voltage is:

$$V_{O} = V_{ref} \cdot \left(1 + \frac{R1}{R2}\right)$$

where

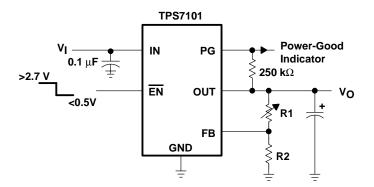
 V_{ref} = reference voltage, 1.178 V typ

APPLICATION INFORMATION

programming the TPS7101 adjustable LDO regulator (continued)

Resistors R1 and R2 should be chosen for approximately 7- μ A divider current. A recommended value for R2 is 169 k Ω with R1 adjusted for the desired output voltage. Smaller resistors can be used, but offer no inherent advantage and consume more power. Larger values of R1 and R2 should be avoided as leakage currents at FB introduce an error. Solving equation 1 for R1 yields a more useful equation for choosing the appropriate resistance:

$$R1 = \left(\frac{V_O}{V_{ref}} - 1\right) \cdot R2$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

T KOOKAWIWIIYO GOIDE										
R1	R2	UNIT								
191	169	kΩ								
309	169	kΩ								
348	169	kΩ								
402	169	kΩ								
549	169	kΩ								
750	169	kΩ								
	R1 191 309 348 402 549	R1 R2 191 169 309 169 348 169 402 169 549 169								

Figure 44. TPS7101 Adjustable LDO Regulator Programming

power-good indicator

The TPS71xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or as a low-battery indicator. PG does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low, relative to its nominal regulated value.

regulator protection

The TPS71xx PMOS-pass transistor has a built-in back diode that safely conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS71xx also features internal current limiting and thermal protection. During normal operation, the TPS71xx limits output current to approximately 1 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 165°C, thermal-protection circuitry shuts it down. Once the device has cooled, regulator operation resumes.







17-Mar-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS7101QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7101QP	Samples
TPS7101QPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7101QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7133QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7133	Samples
TPS7148QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples



PACKAGE OPTION ADDENDUM

17-Mar-2017

Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS7148QPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples
TPS7150QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7150QP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

17-Mar-2017

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

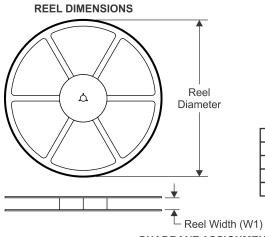
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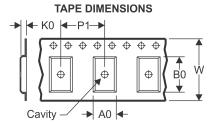
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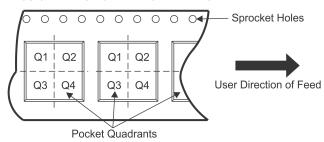
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

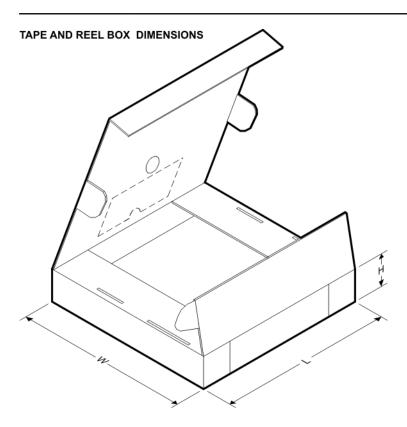
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS7101QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7101QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7133QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7133QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7150QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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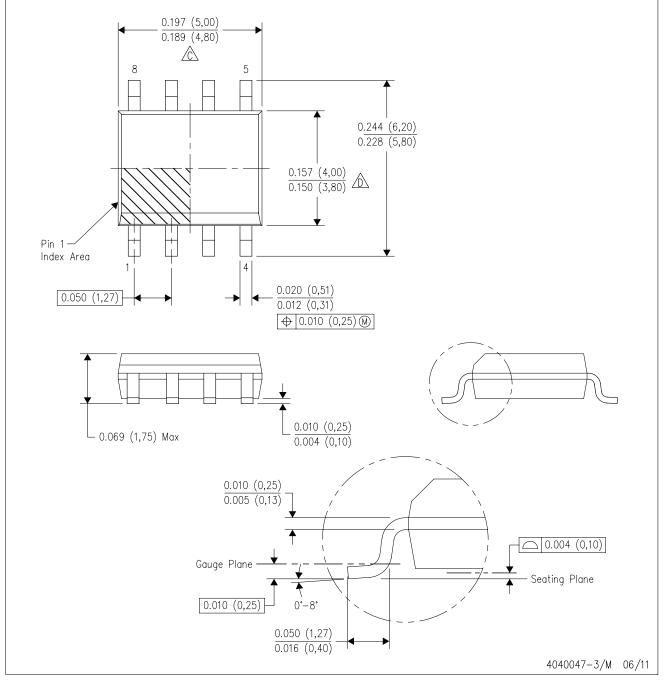


*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS7101QDR	SOIC	D	8	2500	367.0	367.0	35.0
TPS7101QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7133QDR	SOIC	D	8	2500	367.0	367.0	38.0
TPS7133QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7150QDR	SOIC	D	8	2500	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

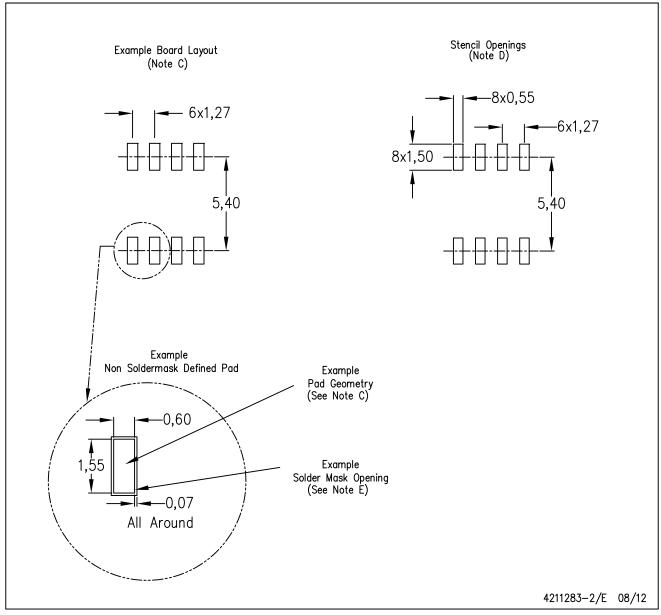


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

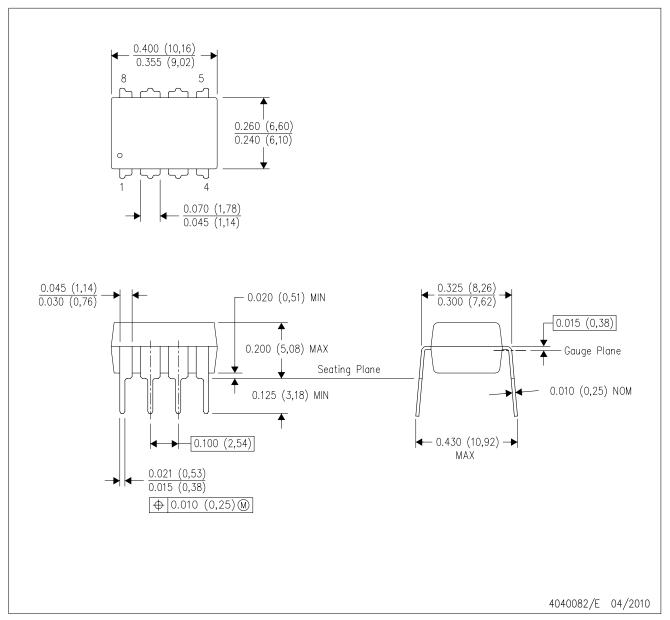


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE

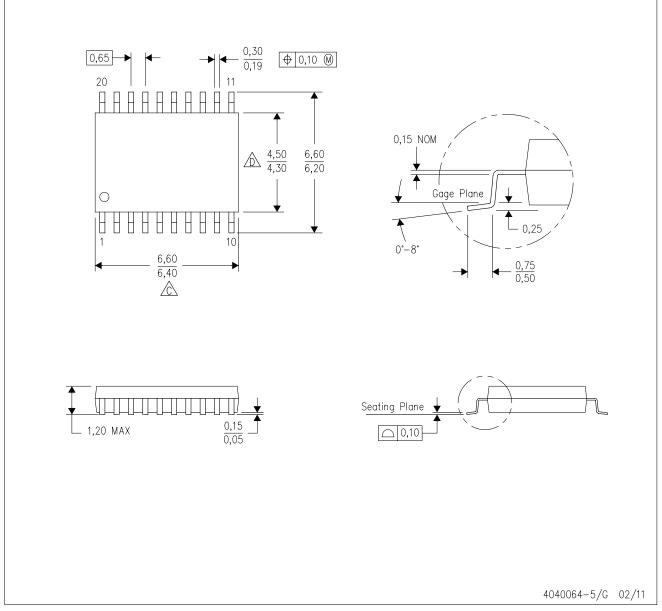


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

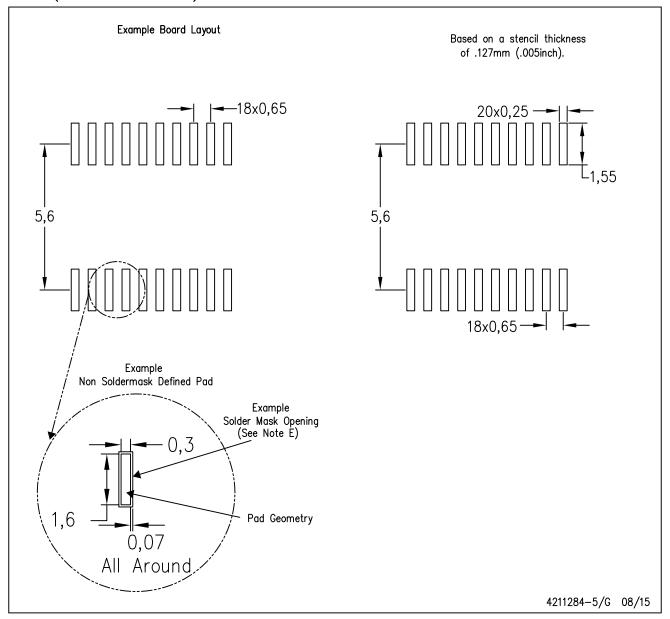


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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